System Design Challenges on AI PC/AI Server

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Abstract
In the process of training artificial intelligence models, issues arising from the massive transmission of information, increased work energy consumption, and increased transmission speed have become an integral part of optimizing product design. In addition to SI/PI design considerations, multi-physical related issues also have a critical impact on product performance.
This talk will cover the development of high-speed circuits, introduce the current design status of system products, and discuss the design and development direction of efficient systems.

Bio
Bin-Chyi Tseng (Senior Member, IEEE) He received the B.S. and B.S.M., M.S., and Ph.D. degrees in communication engineering from the National Yang Ming Chiao Tung University, Hsinchu, Taiwan, in 1994, 1996, and 2004, respectively.
He is double majored in communication engineering and management science. From 1996 to 2001, he was an RF circuit engineer with the Computer and Communication Laboratories, Industrial Technology Research Institute, Hsinchu, where he developed multilayer RF components and modules. In 2001, he joined the Walsin Technology Corporation, Taipei, Taiwan, where he developed low-temperature cofired ceramic RF components and miniaturized WiFi/BT modules. In 2005, he joined the Department of Electrical Engineering, Feng Chia University, Taichung, Taiwan, as an Assistant Professor. In 2013, he joined the ASUSTek Computer Inc., Taipei, Taiwan, and is currently a division director with the Advanced EM Technical Division. His research interests include signal/power integrity, radio frequency interference, computational electromagnetics, design of various electromagnetic compatibility components, numerical simulations, and multilayer RF circuits.

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